

RENESAS SEMICONDUCTOR RELIABILITY REPORT

GROUP : RX621
DEVICE : R5F5621XXX
APPLICATION : Consumer / Industry

Quality Assurance Div.
Renesas Electronics Corporation

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Table. Reliability test results (QFP)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 °C, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 °C, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 °C, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-65 °C to 150 °C , 300 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JEITA ED-4701/302	+/-1000V,1time	0/3	Class: Equivalent to C2b
Solderability (SD)	J-STD-002	245 °C, 5 s, Solder coverage ≥95 %	0/5	
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

*1) With preconditioning per JESD22-A113, MSL 3

·It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :

Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

Table. Reliability test results (BGA)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 °C, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 °C, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 °C, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-55 °C to 125 °C , 500 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JEITA ED-4701/302	+/-1000V,1time	0/3	Class: Equivalent to C2b
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

*1) With preconditioning per JESD22-A113, MSL 3

•It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :

Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

Table. Reliability test results (LGA)

Test Items	Reference	Test Conditions	Results Failure/Size	Comment
High Temperature Operating Life (HTOL)	JESD22-A108	Ta=125 °C, Vccmax, 1000 hrs	0/22	
High Temperature Storage Life (HTSL)	JESD22-A103	Ta=150 °C, 1000 hrs	0/22	
Temperature Humidity bias (THB) (*1)	JESD22-A101	Ta=85 °C, RH=85 %, Vccmax, 1000 hrs	0/22	
Temperature Cycling (TC) (*1)	JESD22-A104	Ta=-55 °C to 125 °C , 500 cycles	0/22	
Latch-Up (LU)	JESD78	Pulse Current Injection, I=+/-150 mA	0/3	
Electrostatic discharge (ESD-HBM)	JS-001	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3	Class: 2
Electrostatic discharge (ESD-CDM)	JEITA ED-4701/302	+/-1000V,1time	0/3	Class: Equivalent to C2b
Resistance to Soldering Heat (PC)	JESD22-A113, J-STD-020	MSL3(Moisture Sensitivity Level 3)	0/22	

*1) With preconditioning per JESD22-A113, MSL 3

•It is tested to confirm that all the samples are satisfied with an individual product specification.

Note :

Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .

The failure rate of the device in an actual use condition can be estimated by the below procedure.

• **Equation for the failure rate estimation (λ)**

$$\lambda = \lambda_b \times \pi T \text{ (FIT)}$$

① Unique failure rate (λ_b)

$$\lambda_b = 0.03 \text{ FIT}$$

Unique failure rate at $T_a = 55^\circ\text{C}$ using 60 % confidence level.

② Temperature term (πT)

$$\pi T = \exp\{11600 \times E_a \times (1/(273+55) - 1/(273+T_a))\}$$

E_a : Activation energy (eV)

T_a : Ambient temperature ($^\circ\text{C}$)

πT simplified chart as $E_a = 0.7 \text{ eV}$

T_a ($^\circ\text{C}$)	40	50	55	60	65	70	75	80	85	90	100	110
πT	0.31	0.68	1	1.45	2.08	2.95	4.15	5.77	7.96	10.88	19.82	34.99

• **MTTF (Mean Time To Failure)**

$$MTTF = 1/\lambda$$

Reference about Renesas package code

Package type		Package code *1
Lead type plastic package	QFP	PxQP
Non-lead type plastic package	QFN	PxQN
Grid array type plastic package	BGA	PxBG
	LGA	PxLG

*1. First four digit

Table. Product list

No	Group	Product part number	Package code	No	Group	Product part number	Package code
1	RX621	R5F56216BDBG	PLBG0176G*	51			
2	RX621	R5F56216BNBG	PLBG0176G*	52			
3	RX621	R5F56217BDBG	PLBG0176G*	53			
4	RX621	R5F56217BNBG	PLBG0176G*	54			
5	RX621	R5F56218BDBG	PLBG0176G*	55			
6	RX621	R5F56218BNBG	PLBG0176G*	56			
7	RX621	R5F56216BDFB	PLQP0144K*	57			
8	RX621	R5F56216BNFB	PLQP0144K*	58			
9	RX621	R5F56217BDFB	PLQP0144K*	59			
10	RX621	R5F56217BNFB	PLQP0144K*	60			
11	RX621	R5F56218BDFB	PLQP0144K*	61			
12	RX621	R5F56218BNFB	PLQP0144K*	62			
13	RX621	R5F56216BDFP	PLQP0100K*	63			
14	RX621	R5F56216BNFP	PLQP0100K*	64			
15	RX621	R5F56217BDFP	PLQP0100K*	65			
16	RX621	R5F56217BNFP	PLQP0100K*	66			
17	RX621	R5F56218BDFP	PLQP0100K*	67			
18	RX621	R5F56218BNFP	PLQP0100K*	68			
19	RX621	R5F56216BDLD	PTLG0085J*	69			
20	RX621	R5F56216BNLD	PTLG0085J*	70			
21	RX621	R5F56217BDLD	PTLG0085J*	71			
22	RX621	R5F56217BNLD	PTLG0085J*	72			
23	RX621	R5F56218BDLD	PTLG0085J*	73			
24	RX621	R5F56218BNLD	PTLG0085J*	74			
25	RX621	R5F56216BDLE	PTLG0145J*	75			
26	RX621	R5F56216BNLE	PTLG0145J*	76			
27	RX621	R5F56217BDLE	PTLG0145J*	77			
28	RX621	R5F56217BNLE	PTLG0145J*	78			
29	RX621	R5F56218BDLE	PTLG0145J*	79			
30	RX621	R5F56218BNLE	PTLG0145J*	80			
31				81			
32				82			
33				83			
34				84			
35				85			
36				86			
37				87			
38				88			
39				89			
40				90			
41				91			
42				92			
43				93			
44				94			
45				95			
46				96			
47				97			
48				98			
49				99			
50				100			